

# NPN General-Purpose Amplifier

# **NSVT5551MR6**

#### **Features**

- This Device Has Matched Dies
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### **ABSOLUTE MAXIMUM RATINGS**

(T<sub>A</sub> = 25°C, unless otherwise noted)

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	$V_{CEO}$	160	V
Collector - Base Voltage	V <sub>CBO</sub>	180	V
Emitter - Base Voltage	V <sub>EBO</sub>	6	V
Collector Current - Continuous	I <sub>C</sub>	600	mA
Junction Temperature	$T_J$	150	°C
Storage Temperature Range	T <sub>STG</sub>	-55 to 150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## THERMAL CHARACTERISTICS (Notes 1, 2)

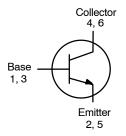
(T<sub>A</sub> = 25°C, unless otherwise noted)

Characteristic	Symbol	Max	Unit
Power Dissipation (T <sub>C</sub> = 25°C)	$P_{D}$	0.7	W
Derate Above 25°C		5.6	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	180	°C/W

- 1.  $P_D$  total, for both transistors. For each transistor,  $P_D$  = 350 mW.
- 2. PCB size: FR-4, 76 mm x 114 mm x 1.57 mm (3.0 inch x 4.5 inch x 0.062 inch) with minimum land pattern size.

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## **ELECTRICAL CONNECTION**





TSOT23 6-Lead CASE 419BL

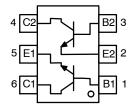
## **MARKING DIAGRAM**



3S2 = Specific Device Code

M = Date Code

#### **PIN ASSIGNMENT**



### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NSVT5551MR6T1G	TSOT23-6 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## NSVT5551MR6

## **ELECTRICAL CHARACTERISTICS** ( $T_A = 25$ °C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Max	Unit
Collector-Emitter Breakdown Voltage	BV <sub>CEO</sub>	I <sub>C</sub> = 1 mA, I <sub>B</sub> = 0	160	-	V
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	$I_C = 100 \mu A, I_E = 0$	180	-	V
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	$I_E = 10 \mu A, I_C = 0$	6	-	V
Collector Cut-Off Current	I <sub>CBO</sub>	V <sub>CB</sub> = 120 V, I <sub>E</sub> = 0	-	50	nA
		V <sub>CB</sub> = 120 V, I <sub>E</sub> = 0, T <sub>A</sub> = 100°C	-	50	μΑ
Emitter Cut-Off Current	I <sub>EBO</sub>	$V_{EB} = 4 \text{ V}, I_{C} = 0$	-	50	nA
DC Current Gain	h <sub>FE1</sub>	V <sub>CE</sub> = 5 V, I <sub>C</sub> = 1 mA	80	-	-
Variation Ratio of h <sub>FE1</sub> Between Die 1 and Die 2	DIVID1	h <sub>FE1</sub> (Die1) / h <sub>FE1</sub> (Die2)	0.9	1.1	-
DC Current Gain	h <sub>FE2</sub>	$V_{CE} = 5 \text{ V}, I_{C} = 10 \text{ mA}$	80	250	-
Variation Ratio of h <sub>FE2</sub> Between Die 1 and Die 2	DIVID2	h <sub>FE2</sub> (Die1) / h <sub>FE2</sub> (Die2)	0.95	1.05	-
DC Current Gain	h <sub>FE3</sub>	V <sub>CE</sub> = 5 V, I <sub>C</sub> = 50 mA	30	-	-
Variation Ratio of h <sub>FE3</sub> Between Die 1 and Die 2	DIVID3	h <sub>FE3</sub> (Die1) / h <sub>FE3</sub> (Die2)	0.9	1.1	-
Collector-Emitter Saturation Voltage	V <sub>CE</sub> (sat)	I <sub>C</sub> = 10 mA, I <sub>B</sub> = 1 mA	-	0.15	V
		I <sub>C</sub> = 50 mA, I <sub>B</sub> = 5 mA	-	0.20	
Base-Emitter Saturation Voltage	V <sub>BE</sub> (sat)	I <sub>C</sub> = 10 mA, I <sub>B</sub> = 1 mA	-	1	V
		I <sub>C</sub> = 50 mA, I <sub>B</sub> = 5 mA	-	1	
Base-Emitter On Voltage	V <sub>BE</sub> (on)	V <sub>CE</sub> = 5 V, I <sub>C</sub> = 10 mA	-	1	V
Difference of V <sub>BE</sub> (on) Between Die1 and Die 2	DEL	V <sub>BE</sub> (on)(Die) – V <sub>BE</sub> (on)(Die2)	-8	8	mV
Output Capacitance	C <sub>ob</sub>	V <sub>CB</sub> = 10 V, I <sub>E</sub> = 0, f = 1 MHz	-	6	pF
Input Capacitance	C <sub>ib</sub>	V <sub>EB</sub> = 0.5 V, I <sub>C</sub> = 0, f = 1 MHz	-	20	pF
Current Gain Bandwidth Product	f <sub>T</sub>	V <sub>CE</sub> = 10 V, I <sub>C</sub> = 10 mA, f = 100 MHz	100	300	MHz
Noise Figure	NF	$V_{CE}$ = 5 V, $I_{C}$ = 200 μA, f = 1 MHz, $R_{S}$ = 20 kΩ, B = 200 Hz	-	8	dB
Small Signal Current Gain	h <sub>fe</sub>	$V_{CE} = 10 \text{ V}, I_{C} = 1.0 \text{ mA},$ f = 10 kHz	50	250	-

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## NSVT5551MR6

## TYPICAL PERFORMANCE CHARACTERISTICS

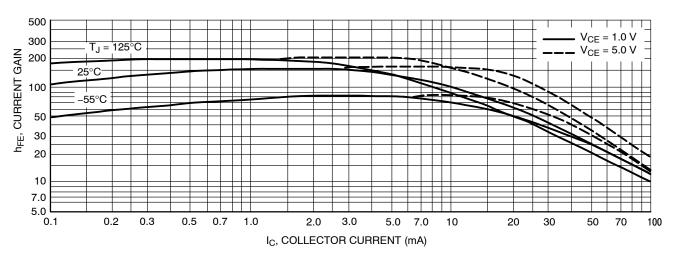


Figure 1. DC Current Gain

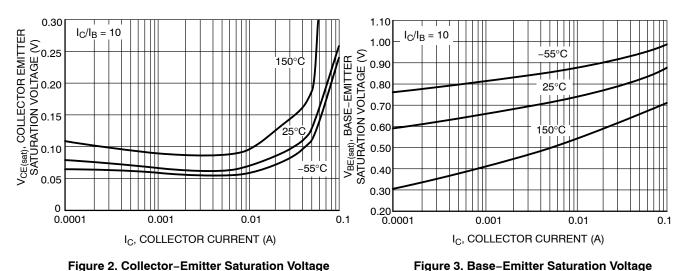


Figure 2. Collector-Emitter Saturation Voltage vs. Collector Current

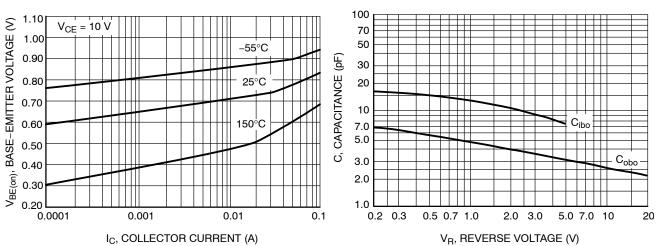


Figure 4. Base-Emitter On Voltage vs. Collector Current

Figure 5. Capacitances

vs. Collector Current



0.20 C

// 0.10 C

0.10 C



PIN 1 **IDENTIFIER** 

## TSOT23 6-Lead CASE 419BL **ISSUE A**

-[A]

F1

-b

A2

C

GAGE PLANE

SEATING PLANE

A1-

e1 TOP VIEW

FRONT VIEW

**DETAIL A** 

В

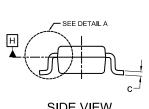
0.20 C

**DATE 31 AUG 2020** 

#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- CONTROLLING DIMENSION: MILLIMETERS
  DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,
  PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.25MM PER END. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM H.
- 4. SEATING PLANE IS DEFINED BY THE TERMINALS. "A1" IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

DIM L

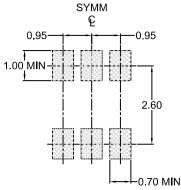


DIM	MIN.	NOM.	MAX.
Α	0.90	1.00	1.10
A1	0.00	0.05	0.10
A2	0.70	0.85	1.00
А3	0.25 BSC		
b	0.25	0.38	0.50
С	0.10	0.18	0.26
D	2.80	2.95	3.10
d	0.30 REF		
E	2.50	2.75	3.00
E1	1.30	1.50	1.70
е	0.95 BSC		
e1	1.90 BSC		
L1	0.60 REF		
L2	0.20	0.40	0.60
θ	0°		10°

MILLIMETERS



SIDE VIEW



## LAND PATTERN RECOMMENDATION

\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.





XXX = Specific Device Code

= Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	TSOT23 6-Lead		PAGE 1 OF 1

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